

IGTH10N40 IGM10N40 IGTP10N40
IGTH10N40A IGM10N40A IGTP10N40A
IGTH10N50 IGM10N50 IGTP10N50
IGTH10N50A IGM10N50A IGTP10N50A

N-Channel Enhancement Mode Conductivity-Modulated Power Field-Effect Transistors

10 A, 400 V and 500 V

$V_{CE(on)}$: 2.5 V

$T_{f\downarrow}$: 1 μ s, 0.5 μ s

Features:

- Low on-state voltage
- Fast switching speeds
- High input impedance
- No anti-parallel diode

Applications:

- Power supplies
- Motor drives
- Protective circuits

The IGTH10N40, IGTH10N40A, IGTH10N50, IGTH10N50A, IGTP10N40, IGTP10N40A, IGTP10N50, IGTP10N50A, IGTM10N40, IGTM10N40A, IGTM10N50, IGTM10N50A* are n-channel enhancement-mode conductivity-modulated power field-effect transistors (COMFETs) designed for high-voltage, low on-dissipation applications such as switching regulators and motor drivers. These types can be operated directly from low-power integrated circuits.

The IGTH-types are supplied in the JEDEC TO-218AC plastic package and the IGTP-types in the JEDEC TO-220AB plastic package.

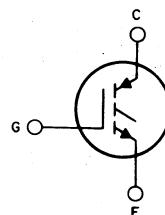
The IGM-types are supplied in the JEDEC TO-204AA steel package.

*The IGTH and IGTP series were formerly RCA Development Type Nos. TA9687 and TA9438, respectively. The IGM series was formerly RCA Development Type No. TA9437.

MAXIMUM RATINGS,

Absolute-Maximum Values ($T_c = 25^\circ C$):

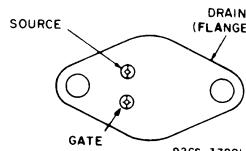
TERMINAL DIAGRAM



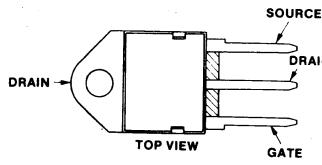
92CS-43134

N-CHANNEL ENHANCEMENT MODE

TERMINAL DESIGNATION



JEDEC TO-204AA



92CS-39967

JEDEC TO-218AC

	IGTH10N40	IGTH10N50	IGTH10N40A	IGTH10N50A	IGM10N40	IGM10N50	IGTP10N40	IGTP10N50	IGTP10N40A	IGTP10N50A	
COLLECTOR-EMITTER VOLTAGE, V_{CES}	400	500	400	500	400	500	400	500	400	500	V
COLLECTOR-GATE VOLTAGE ($R_{ce} = 1 M\Omega$), V_{CGR}	400	500	400	500	-	-	-	-	-	-	V
REVERSE COLLECTOR-EMITTER VOLTAGE, $V_{CES(rev)}$	-	-	-	-	-	-	-	-	-	-	V
GATE-EMITTER VOLTAGE, V_{GE}	-	-	-	-	-	-	-	-	-	-	V
COLLECTOR CURRENT, RMS Continuous, I_c	-	-	-	-	-	-	-	-	-	-	A
Pulsed, I_{cm}	-	-	-	-	-	-	-	-	-	-	A
POWER DISSIPATION @ $T_c = 25^\circ C$, P_T	75	75	60	60	60	60	60	60	60	60	W
Derate above $T_c = 25^\circ C$	0.6	0.6	0.48	0.48	0.48	0.48	0.48	0.48	0.48	0.48	W/ $^\circ C$
OPERATING AND STORAGE TEMPERATURE, T_j , T_{stg}	-	-	-	-	-	-	-	-	-	-	$^\circ C$
	-5 to +150										

Harris Semiconductor IGBT product is covered by one or more of the following U.S. patents:

4,364,073	4,417,385	4,430,792	4,443,931	4,466,176	4,532,534	4,567,641
4,587,713	4,618,872	4,620,211	4,631,564	4,639,754	4,639,762	4,641,162
4,644,637	4,682,195	4,684,413	4,717,679	4,794,432	4,801,986	4,803,533
4,809,045	4,810,665					

IGTH10N40 IGTH10N40A IGTH10N50 IGTH10N50A
 IGM10N40 IGM10N40A IGM10N50 IGM10N50A
 IGTP10N40 IGTP10N40A IGTP10N50 IGTP10N50A

ELECTRICAL CHARACTERISTICS, At Case Temperature ($T_c = 25^\circ C$) unless otherwise specified

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	LIMITS				UNITS
			IGTH10N40	IGTH10N40A	IGTH10N50	IGTH10N50A	
			IGTM10N40	IGTM10N40A	IGTM10N50	IGTM10N50A	
Collector-Emitter Breakdown Voltage	BV_{CES}	$I_C = 1 \text{ mA}$ $V_{GE} = 0$	Min.	Max.	Min.	Max.	V
			400	—	500	—	
Gate Threshold Voltage	$V_{GE(\text{th})}$	$V_{GE} = V_{CE}$ $I_C = 1 \text{ mA}$	2	4.5 3 (typ.)	2	4.5 3 (typ.)	V
Zero-Gate Voltage Collector Current	I_{CES}	$V_{CE} = 400 \text{ V}$ $V_{CE} = 500 \text{ V}$	—	250	—	—	μA
		$T_c = 125^\circ C$ $V_{CE} = 400 \text{ V}$ $V_{CE} = 500 \text{ V}$	—	—	—	—	
		—	—	1000	—	—	
Gate-Emitter Leakage Current	I_{GES}	$V_{GE} = \pm 20 \text{ V}$ $V_{CE} = 0$	—	100	—	100	nA
Collector-Emitter On Voltage	$V_{CE(\text{on})}$	$I_D = 10 \text{ A}$ $V_{GE} = 10 \text{ V}$	—	2.5	—	2.5	V
		$I_C = 17.5 \text{ A}$ $V_{GE} = 20 \text{ V}$	—	3.2	—	3.2	
Gate-Emitter Plateau Voltage	V_{GEP}	$I_C = 5 \text{ A}$ $V_{CE} = 10 \text{ V}$	—	6 (typ.)	—	6 (typ.)	V
On-State Gate Charge	$Q_g(\text{on})$	$I_C = 5 \text{ A}$ $V_{CE} = 10 \text{ V}$	—	19 (typ.)	—	19 (typ.)	nC
Turn-On Delay Time	$t_d(\text{on})$	$I_C = 10 \text{ A}$ $V_{CE(\text{CLP})} = 300 \text{ V}$ $L = 50 \mu\text{H}$ $T_J = 100^\circ C$ $V_{GE} = 10 \text{ V}$ $R_g = 50 \Omega$	—	50	—	50	ns
Rise Time	t_r		—	50	—	50	
Turn-Off Delay Time	$t_d(\text{off})$		—	400	—	400	
Fall Time	t_f		Typ. 680	1000	Typ. 680	1000	
	10N40 10N50		400	500	400	500	
Turn-Off Energy Loss per Cycle (off switching dissipation = $E_{off} \times \text{frequency}$)	E_{off} 10N40 10N50	$I_C = 10 \text{ A}$ $V_{CE(\text{CLP})} = 300 \text{ V}$ $L = 50 \mu\text{H}$ $T_J = 100^\circ C$ $V_{GE} = 10 \text{ V}$ $R_g = 50 \Omega$	680 (typ.)				μJ
	10N40A 10N50A	400 (typ.)					
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	IGTH/IGTM	—	1.67	—	1.67	$^\circ\text{C/W}$
		IGTP	—	2.083	—	2.083	

Insulated-Gate Bipolar Transistors

IGTH10N40 IGTH10N40A IGTH10N50 IGTH10N50A
 IGM10N40 IGM10N40A IGM10N50 IGM10N50A
 IGTP10N40 IGTP10N40A IGTP10N50 IGTP10N50A

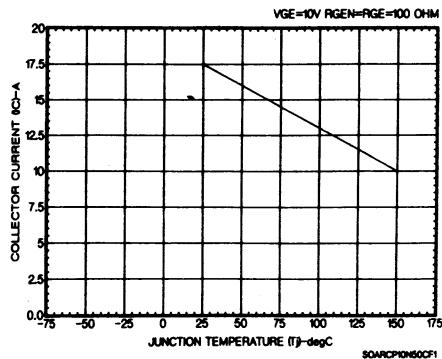


Fig. 1 - Maximum switching current level for all types. $R_g = 50 \Omega$, $V_{GE} = 0$ V are the minimum allowable values.

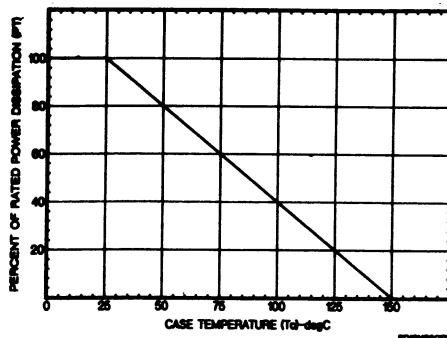


Fig. 2 - Power dissipation vs. temperature derating curve for all types.

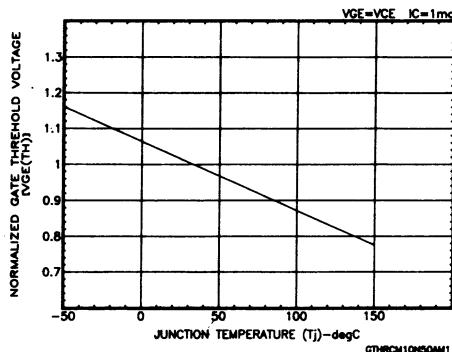


Fig. 3 - Typical normalized gate threshold voltage as a function of junction temperature for all types.

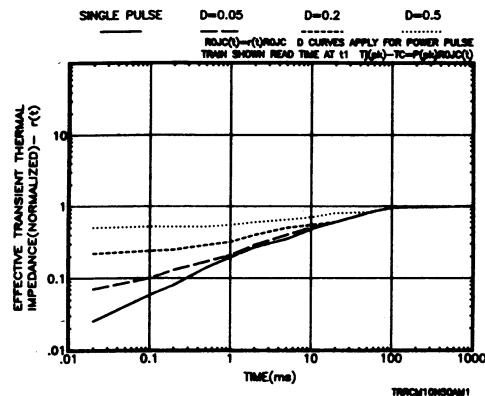


Fig. 4 - Normalized thermal response characteristics for all types.

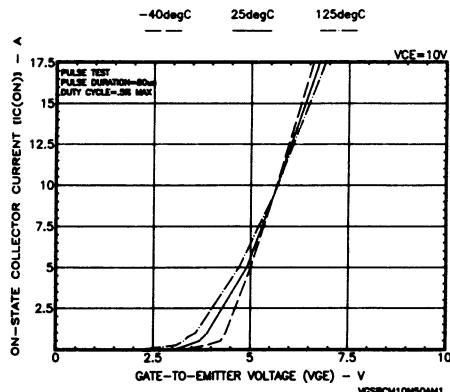


Fig. 5 - Typical transfer characteristics for all types.

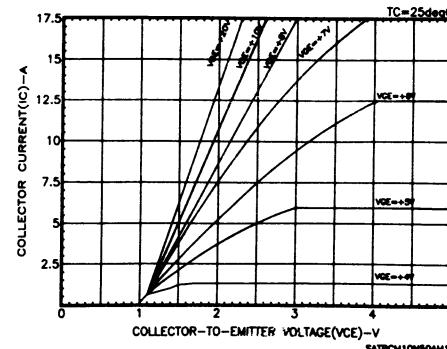
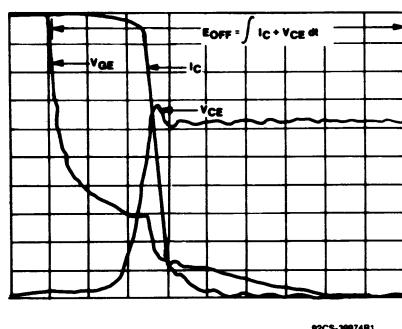
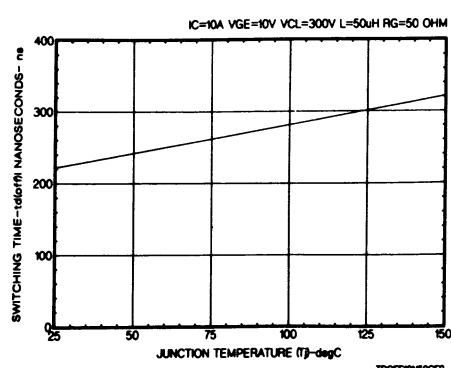
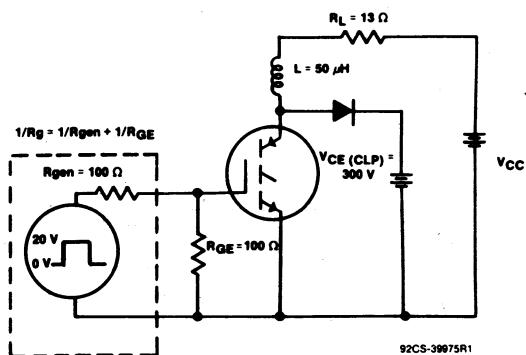
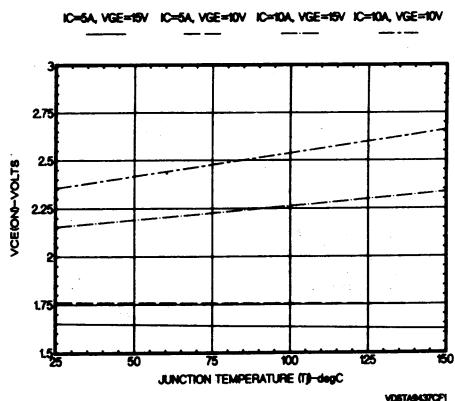
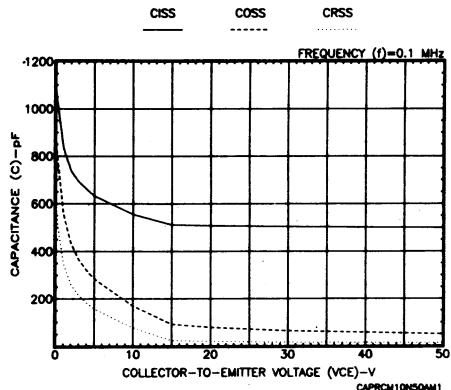
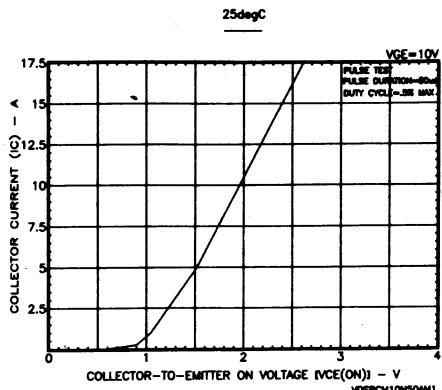


Fig. 6 - Typical saturation characteristics for all types.

IGTH10N40	IGTH10N40A	IGTH10N50	IGTH10N50A
IGTM10N40	IGTM10N40A	IGTM10N50	IGTM10N50A
IGTP10N40	IGTP10N40A	IGTP10N50	IGTP10N50A



IGTH10N40 IGTH10N40A IGTH10N50 IGTH10N50A
 IGBTM10N40 IGBTM10N40A IGBTM10N50 IGBTM10N50A
 IGBTP10N40 IGBTP10N40A IGBTP10N50 IGBTP10N50A

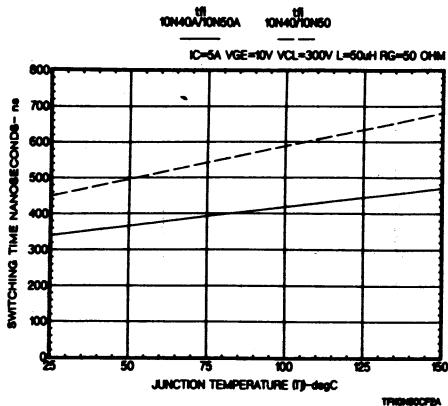


Fig. 13 - Typical fall time for all types ($I_c = 5$ A).

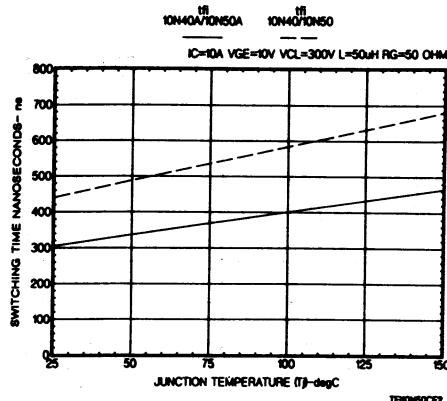


Fig. 14 - Typical fall time for all types ($I_c = 10$ A).

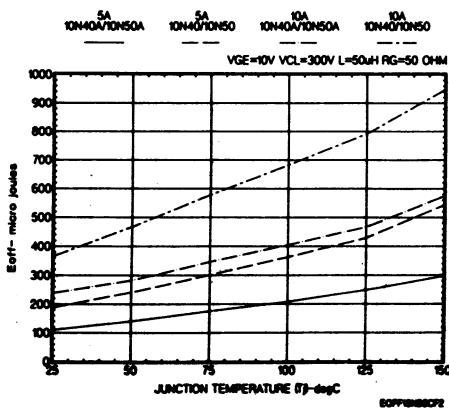
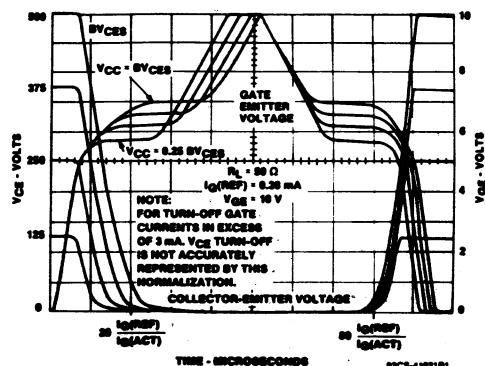


Fig. 15 - Typical clamped inductive turn-off switching loss/cycle.



Refer to RCA application notes AN-7254 and AN-7260 on the use of normalized switching waveforms.

Fig. 16 - Normalized switching waveforms at constant gate current.

N-Channel Enhancement-Mode Insulated Gate Bipolar Transistors (IGBTs) With Anti-Parallel Ultra-Fast Diode

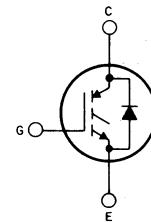
10 A, 400 V and 500 V

V_{ce(on)}: 2.5 V MaximumT_{fall}: 1 μ s, 0.5 μ s**Features:**

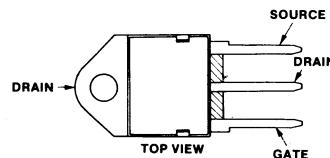
- Low on-state voltage
- Fast switching speeds
- High input impedance
- Anti-parallel diode

Applications:

- Power supplies
- Motor drives
- Protective circuits

N-CHANNEL ENHANCEMENT MODE

92CS - 43516

TERMINAL DIAGRAM**TERMINAL DESIGNATION**

JEDEC TO-218AC

MAXIMUM RATINGS, Absolute-Maximum Values ($T_c = 25^\circ C$):

	IGTH10N40D IGTH10N40AD	IGTH10N50D IGTH10N50AD	
COLLECTOR-EMITTER VOLTAGE	V _{CES} 400	500	V
COLLECTOR-GATE VOLTAGE ($R_{g\theta} = 1 \text{ M}\Omega$)	V _{CGR} 400	500	V
GATE-EMITTER VOLTAGE	V _{GE}	±20	V
COLLECTOR CURRENT, RMS Continuous	I _C Pulsed	10	A
POWER DISSIPATION at $T_c = 25^\circ C$	P _T Derate above $T_c = 25^\circ C$	17.5	A
OPERATING AND STORAGE TEMPERATURE	T _J , T _S	75	W
		0.6	°C
		-55 to +150	

Harris Semiconductor IGBT product is covered by one or more of the following U.S. patents:

4,364,073	4,417,385	4,430,792	4,443,931	4,466,176	4,532,534	4,567,641
4,587,713	4,618,872	4,620,211	4,631,564	4,639,754	4,639,762	4,641,162
4,644,637	4,682,195	4,684,413	4,717,679	4,794,432	4,801,986	4,803,533
4,809,045	4,810,665					

IGTH10N40D, IGTH10N40AD, IGTH10N50D, IGTH10N50ADELECTRICAL CHARACTERISTICS, At Case Temperature ($T_c = 25^\circ\text{C}$) unless otherwise specified

CHARACTERISTIC	TEST CONDITIONS	LIMITS				UNITS	
		IGTH10N40D IGTH10N40AD		IGTH10N50D IGTH10N50AD			
		MIN.	MAX.	MIN.	MAX.		
Collector-Emitter Breakdown Voltage BV_{CES}	$I_c = 1 \text{ mA}$ $V_{\text{GE}} = 0$	400	—	500	—	V	
Gate Threshold Voltage $V_{\text{GE}}(\text{th})$	$V_{\text{GE}} = V_{\text{CE}}$ $I_c = 1 \text{ mA}$	2	4.5	2	4.5		
Zero-Gate Voltage Collector Current I_{CES}	$V_{\text{CE}} = 400 \text{ V}$ $V_{\text{CE}} = 500 \text{ V}$	—	250	—	—	μA	
	$T_c = 125^\circ\text{C}$ $V_{\text{CE}} = 400 \text{ V}$ $V_{\text{CE}} = 500 \text{ V}$	—	—	—	—		
	$V_{\text{GE}} = \pm 20 \text{ V}$ $V_{\text{CE}} = 0$	—	100	—	100		
Gate-Emitter Leakage Current I_{GES}	$I_c = 10 \text{ A}$ $V_{\text{GE}} = 10 \text{ V}$	—	2.5	—	2.5		
Collector-Emitter On-Voltage $V_{\text{CE}(\text{on})}$	$I_c = 17.5 \text{ A}$ $V_{\text{GE}} = 20 \text{ V}$	—	3.2	—	3.2	V	
	$I_c = 5 \text{ A}$ $V_{\text{CE}} = 10 \text{ V}$	—	6 (typ)	—	6 (typ)		
On-State Gate Charge $Q_{\text{G}(\text{on})}$	$I_c = 5 \text{ A}$ $V_{\text{CE}} = 10 \text{ V}$	—	19(typ)	—	19(typ)	nC	
Turn-On Delay Time $t_d(\text{on})$	$I_c = 10 \text{ A}$ $V_{\text{CE}(\text{clp})} = 300 \text{ V}$	—	50	—	50	ns	
Rise Time t_r	—	50	—	50	—		
Turn-Off Delay Time $t_d(\text{off})$	—	400	—	400	—		
Fall Time t_f	$L = 50 \mu\text{H}$ $T_J = 100^\circ\text{C}$ $V_{\text{GE}} = 10 \text{ V}$ $R_g = 50 \Omega$	TYP 680	1000	TYP 680	1000		
Turn-Off Energy Loss per Cycle (off switching dissipation = $E_{\text{off}} \times \text{frequency}$)	E_{off} 10N40D 20N50D	$I_c = 10 \text{ A}$ $V_{\text{CE}(\text{clp})} = 300 \text{ V}$ $L = 50 \mu\text{H}$ $T_J = 100^\circ\text{C}$ $V_{\text{GE}} = 10 \text{ V}$ $R_g = 50 \Omega$	1810 (typ)			μJ	
	10N40AD 10N50AD	1070 (typ)					
Thermal Resistance Junction-to-Case $R_{\theta_{\text{JC}}}$	$R_{\theta_{\text{JC}}}$	—	1.67	—	1.67	$^\circ\text{C/W}$	
Diode Forward Voltage V_{EC}	$I_{\text{EC}} = 10 \text{ A}$	—	2	—	2	V	
Diode Reverse Recovery Time T_{rr}	$I_{\text{EC}} = 10 \text{ A}$ $dI/dt = 100 \text{ A}/\mu\text{s}$	—	100	—	100	ns	

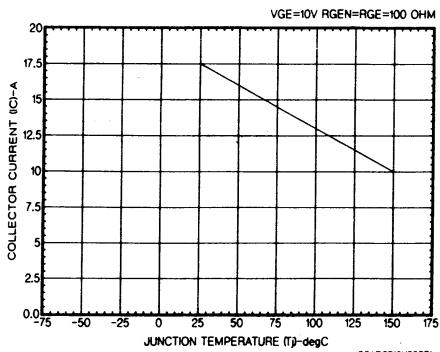


Fig. 1 - Maximum switching current level for all types.
Minimum allowable values are $R_g = 50 \Omega$, $V_{\text{GE}} = 0 \text{ V}$.

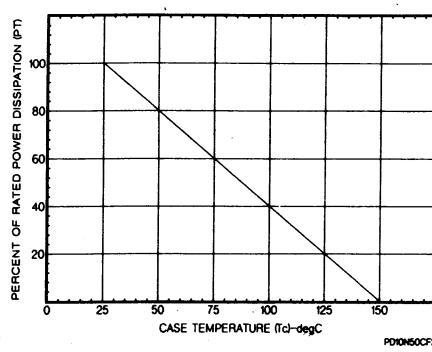


Fig. 2 - Power dissipation vs. temperature derating curve for all types.

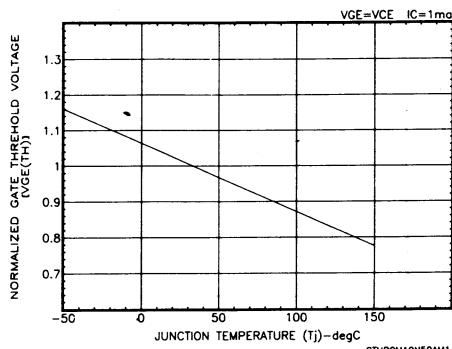
IGTH10N40D, IGTH10N40AD, IGTH10N50D, IGTH10N50AD

Fig. 3 - Typical normalized gate-threshold voltage as a function of junction temperature for all types.

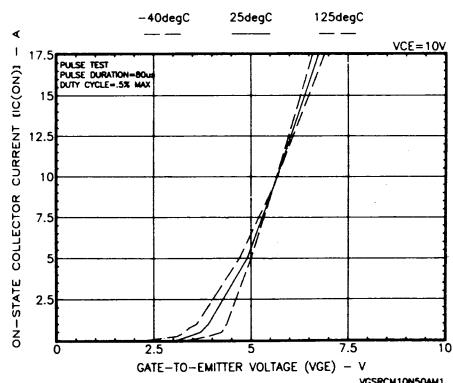


Fig. 4 - Typical transfer characteristics for all types.

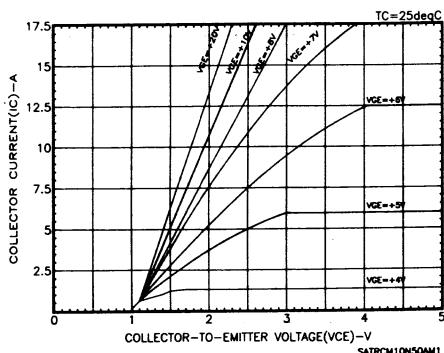


Fig. 5 - Typical saturation characteristics for all types.

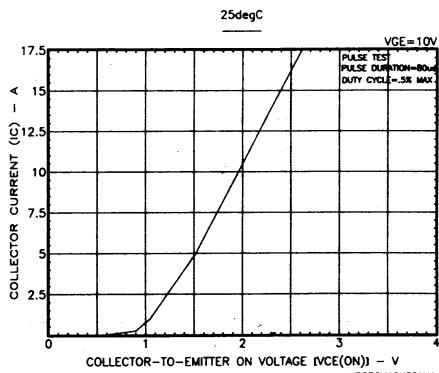


Fig. 6 - Typical collector-to-emitter on-voltage as a function of collector current for all types.

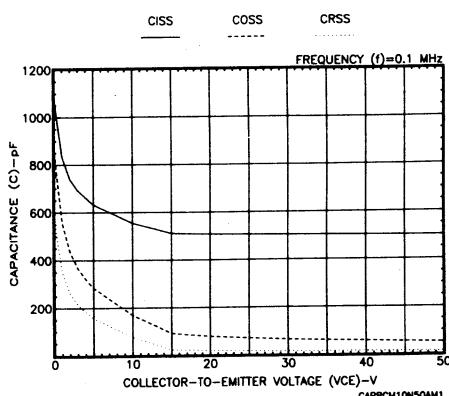


Fig. 7 - Capacitance as a function of collector-to-emitter voltage for all types.

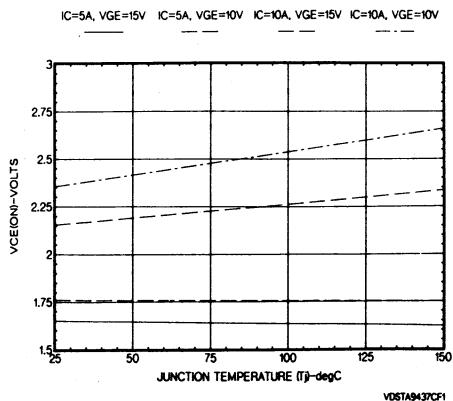


Fig. 8 - Typical $V_{ce(on)}$ vs. temperature for all types.

IGTH10N40D, IGTH10N40AD, IGTH10N50D, IGTH10N50AD

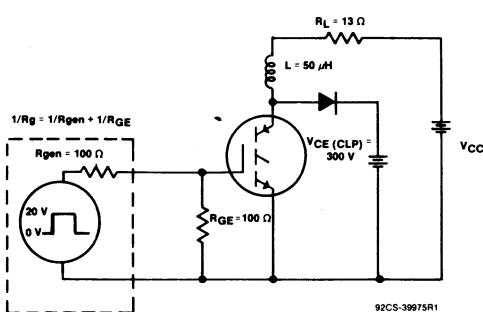


Fig. 9 - Inductive switching test circuit.

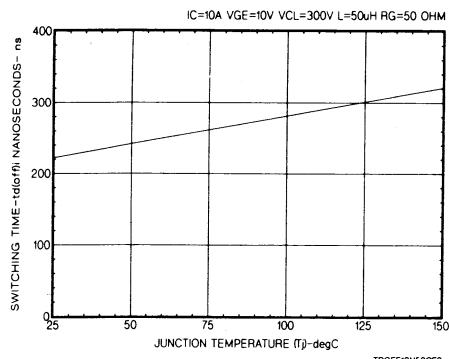


Fig. 10 - Typical turn-off delay time for all types.

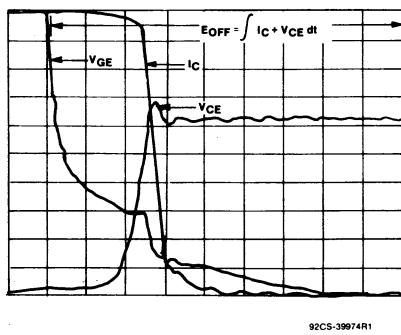


Fig. 11 - Typical inductive switching waveforms.

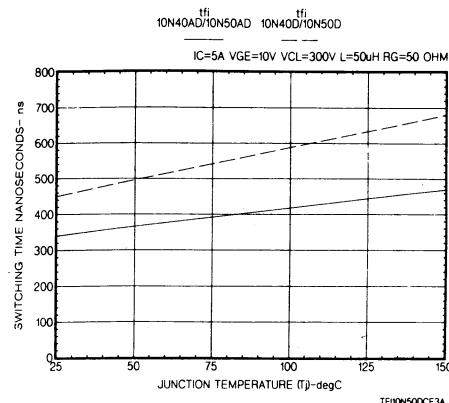


Fig. 12 - Typical fall time for all types ($I_c = 5 A$).

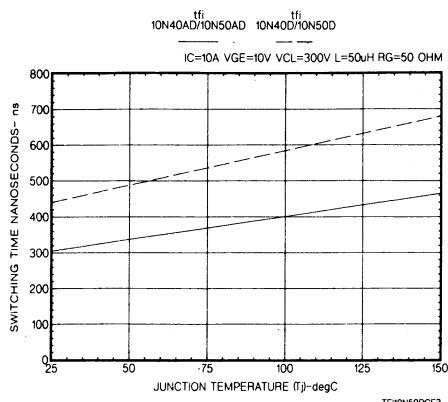


Fig. 13 - Typical fall time for all types ($I_c = 10 A$).

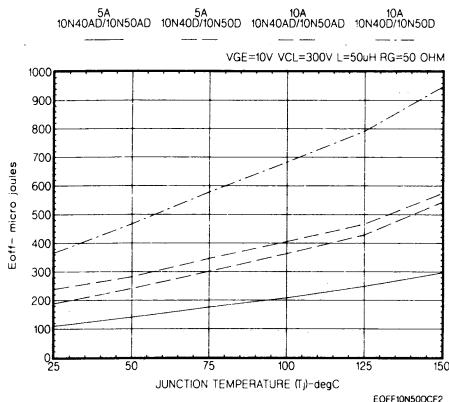


Fig. 14 - Typical clamped inductive turn-off switching loss/cycle.

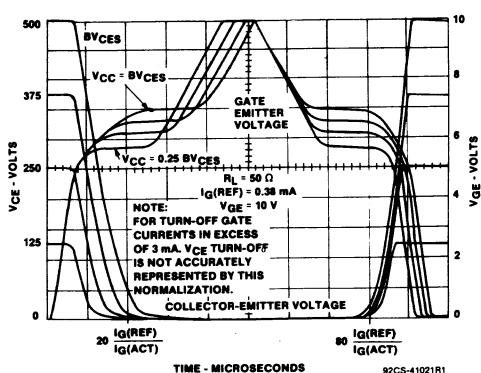
IGTH10N40D, IGTH10N40AD, IGTH10N50D, IGTH10N50AD

Fig. 15 - Normalized switching waveforms at constant gate current.
(Refer to RCA application notes AN7254 and AN7260.)

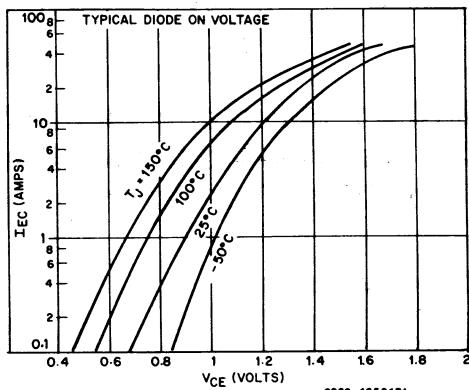


Fig. 16 - Typical diode collector-to-emitter voltage vs.
current for all types.

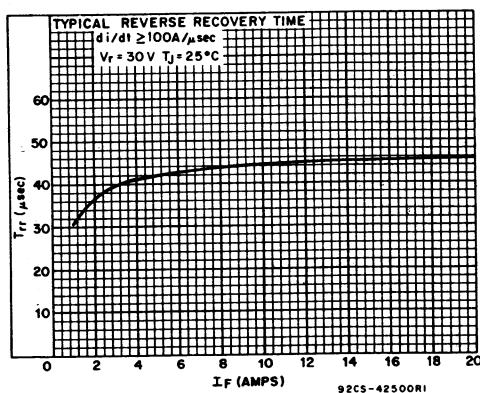


Fig. 17 - Typical diode reverse-recovery time for all types.